

PRODUCT DATA SHEET

SikaBond®-T17

ONE-COMPONENT, LOW ODOR, POLYURETHANE ADHESIVE FOR WOOD FLOORING

PRODUCT DESCRIPTION

SikaBond®-T17 is a one-component, low-VOC, low odor, moisture cured polyurethane adhesive for full surface bonding of wood flooring. SikaBond®-T17 will tenaciously bond wood to most surfaces, including concrete, plywood, and leveling and patch underlayments that have been properly prepared.

USES

SikaBond®-T17 may be used to bond all engineered wood flooring, solid flat-milled shorts and solid shorts designed by the manufacturer for glue down applications. This adhesive can also be used for many other bonding applications that are common for light commercial and residential applications including acoustic rubber underlayment systems.

CHARACTERISTICS / ADVANTAGES

- ~100% elongation
- Bonds up to 3/4" solid and engineered wood
- Low odor
- Excellent workability
- Fast curing
- Suitable for common types of wood floors
- Suitable for in-floor radiant heat installation
- Contains no water
- Tenacious bond

APPROVALS / STANDARDS

LEED® V4.1 CDPH Standard Method v1.2	SCAQMD, Rule 1168 (20 g/L limit)	BAAQMD, Reg. 8, Rule 51-226 (20 g/L limit)
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PRODUCT INFORMATION





Chemical Base	1-component, moisture cured polyurethane
Packaging	4 gal. (15.14 L) pail
Color	Light yellow
Shelf Life	12 months from date of production if stored in undamaged original sealed containers per storage requirements
Storage Conditions	In dry conditions and protected from direct sunlight at temperatures between 50°F and 77°F (10°C and 25°C). Condition material to 65–75°F (18–24°C) before using.



TECHNICAL INFORMATION

Testing	~50	(28 days at 73°F (23°C) and 50 % RH)
Tensile Strength	~150 psi	(28 days at 73°F (23°C) and 50 % RH)
Elongation at Break	~100% cured	(at 73°F (23°C) and 50 % RH)
Service Temperature	-40°F (-40°C) to 158°F (70°C)	


APPLICATION INFORMATION

Coverage

FOR USE AS ADHESIVE ONLY			
Flooring Type		Trowel	Coverage
Solid	Max Thickness: 3/4" Max Width: 5"	1/4" x 1/4" x 1/4" Square notch 	30 sq.ft. per gal.
Engineered	Thickness: >1/2" Max Width: Unlimited	1/4" x 1/4" x 1/8" Square notch 	35-40 sq.ft. per gal.
Engineered	Thickness: <1/2" Max Width: Unlimited	P5: 3/16" x 3/16" x 3/16" Flat V-notch 	45-50 sq.ft. per gal.
		3/16" x 5/32" V-Notch 	50 sq.ft. per gal.

FOR MOISTURE CONTROL			
Flooring Type		Trowel	Coverage
Solid or Engineered	Solid: Max Thickness: 3/4" Max Width: 5"	1/4" x 1/4" V-Notch 	30-35 sq.ft. per gal.
	Eng: Max Thickness: 3/4" Max Width: Unlimited	SCMB: 1/8" x 5/32" x 3/16" 	30-35 sq.ft. per gal.

For Moisture Control Coverage: 100% adhesive coverage to concrete and 100% adhesive transfer to back of board is required

FOR USE WITH UNDERLAYMENT		
Flooring Type	Trowel	Coverage
Cork or rubber underlayment	1/8" x 1/8" Square notch* 	80 sq.ft. per gal.

*Recommended trowel size for 3.2mm material

- Coverage must be monitored to ensure accuracy of application. Trowel angle may prevent proper coverage.
- Applicator is responsible for periodic inspection of the trowel to check for excessive wear. Worn trowels must be replaced immediately.
- In case of uneven substrates, it may be necessary to use a notched trowel with bigger notches (avert hollow sections).
- Trowel size is recommended to obtain proper coverage larger sizes are acceptable. Excessive amounts of adhesive may cause wood flooring to slide while placing check coverage during installation.
- P5 trowels should be used at 90° angle, SC+MB trowel or 1/4 in. (6.3 mm) x 1/4 in. (6.3 mm) V-notch at 45° angle to subfloor to get stated coverages.
- Substrate quality: Structurally sound, clean, dry, homogeneous, even, free from grease, dust and loose particles, paint, laitance, and other poorly adhering particles must be removed.

	<ul style="list-style-type: none"> ▪ The P5 and SC+MB trowel are available from Sika.
Sag Flow	Consistency: spreads easily, holds ridges after troweling
Ambient Air Temperature	Room temperature between 60°F (15°C) and 90°F (32°C). For ambient temperatures the standard construction rules are relevant. Follow all wood floor manufacturer's acclimation and room temperature requirements.
Relative Air Humidity	Between 40% and 70% during installation is best for adhesive. See wood floor manufacturer for wood requirements.
Substrate Temperature	During laying and until SikaBond®-T17 has fully cured, substrate temperature should be greater than 60°F (15°C) and in case of radiant heating, less than 68°F (20°C). For substrate temperatures, the standard construction rules are relevant.
Substrate Moisture Content	<p>For use as an adhesive only: SikaBond®-T17 is not affected by moisture or vapor transmission. For protection of the wood, follow the wood floor manufacturer's requirements for subfloor moisture. If substrate is not acceptable, use SikaBond®-T17 at recommended coverage rate as Moisture Control or Sika® MB. See Technical Data Sheet for proper instruction.</p> <p>For use as an adhesive and moisture membrane: Concrete moisture vapor emission rate (MVER) may not exceed 8 lbs. per 1,000 sq.ft. (3.63 kg per 92.9 m²) per 24 hours, anhydrous calcium chloride test (ASTM F1869). Do not install when the relative humidity (RH) of the concrete slab exceeds 85% (ASTM F2170).</p>
Curing Rate	<p>Floor may accept light foot traffic after:</p> <ul style="list-style-type: none"> ▪ at 45–50 SF/gal (P5 trowel): after 6–8 hr ▪ at 30–35 SF/gal (SC+MB trowel): after ~12 hr <p>(depending on climatic conditions and adhesive layer thickness)</p> <p>Floor can be sanded after ~18 hours</p>
Skin Time / Laying Time	45–60 minutes at 73°F (23°C) and 50% RH

BASIS OF PRODUCT DATA

Results may differ based upon statistical variations depending upon mixing methods and equipment, temperature, application methods, test methods, actual site conditions and curing conditions.

LIMITATIONS

- Wood size limitations can be found in coverage section.
- Room temperatures should be between 50°F (10°C) and 90°F (32°C) during installation unless otherwise specified limitations by wood flooring manufacturer.
- Do not use on wet, contaminated or friable substrates.
- When needed, Sika recommends the use of Sika® Level patching and levelling compounds for best results.
- Gypsum based sub-floors are very susceptible to excess moisture and will be degraded if exposed to excess moisture from below or above.
- Below grade installations are typically more difficult to control moisture and room humidity levels – if this cannot be done sufficiently then below grade applications should use structurally sound engineered hardwood only.
- Do not use in areas subject to hydrostatic head or in areas subject to secondary source of moisture.
- Do not use over concrete with curing compounds, sealers or other surface treatments that could impact the adhesion.
- This adhesive will not prevent excessive moisture related damage to wood flooring installations.
- Subfloor should be level – do not use adhesive as a levelling agent.
- Contact with SikaBond® Remover will inhibit cure.
- Cutback or asphaltic based residue must be removed before use of adhesive.
- Sufficient ambient moisture is necessary for proper curing.
- During laying, and until SikaBond®-T17 has fully cured, substrate temperature should be greater than 60°F (15°C). For substrate temperatures, the standard construction rules are relevant.
- Installations over radiant heat require that slab temperature be kept below 68°F (20°C) during installation and for 48 hours after installation – then raised slowly up to final desired temperature. Follow wood floor manufacturer's temperature guidelines.

Wood floors in non-insulated areas or areas without a moisture protection membrane, must only be installed after the application of Sika® MB to control the moisture, if within product limitations. For detailed instructions consult the Product Data Sheets or contact our Technical Service. In case of chemically pre-treated types of wood floors (e.g. ammonia, wood stain, timber preservative or woods that have been pre-sealed on the back side) and woods with high oil content SikaBond® should only be used if adhesion tests are run by applicator prior to starting application. Do not use on PE, PP, TEFLON, and certain plasticized synthetic materials. (Carry out pre-trials). Some primers can negatively influence the adhesion of SikaBond® (pre-trials suggested). Do not expose SikaBond® to alcohol; this will impact the curing of the SikaBond®.

ENVIRONMENTAL, HEALTH AND SAFETY

For further information and advice regarding transportation, handling, storage and disposal of chemical products, user should refer to the actual Safety Data Sheets containing physical, environmental, toxicological and other safety related data. User must read the current actual Safety Data Sheets before using any products. In case of an emergency, call CHEMTREC at 1-800-424-9300, International 703-527-3887.

APPLICATION INSTRUCTIONS

SUBSTRATE QUALITY

Substrate must be clean and dry, homogeneous, even, free from grease, dust and loose particles. Paint, laitance and other poorly adhering particles must be removed by mechanical means.

SUBSTRATE PREPARATION

- SikaBond®-T17 can be used on properly prepared, structurally sound concrete, cementitious patch/underlayments, chipboards, ceramic tiles, plywood.
- Concrete substrate must have a concrete surface profile of CSP 1-3.
- For on-grade subfloors Sika recommends the use of Sika® MB, Sika® MB Redline, and Sika® MB EZ Rapid for best protection against sub-floor moisture – moisture testing is required by the wood flooring manufacturer for best results with the wood flooring products.
- Below grade applications are generally not recommended unless proper precautions are taken to protect the wood flooring from sub-floor and in-room humidity extremes.
- A 3,000 psi compressive strength is the minimum requirement needed for SikaBond® wood floor installations, including glue-down wood floors, or glued/mechanically anchored subfloors. Sika products such as Sika® Level-01 Primer Plus, Sika® MB, Sika® MB

Redline, and Sika® MB EZ Rapid can be used on substrates as consolidators to satisfy the minimum psi compressive strength requirements.

- Preparation is a critical step in the installation process and will ensure a successful long term tenacious bond.
- All concrete, cement screed and gypsum based subfloors must be structurally sound, clean, dry, smooth; free of voids, projections, loose materials, oil, grease, sealers and other surface contaminants. Thoroughly clean with an industrial vacuum. Remove laitance or weak areas mechanically and thoroughly.
- For application over ceramic tiles it is necessary to grind tile surfaces and clean thoroughly with an industrial vacuum.
- For substrates with old well bonded non-water soluble adhesive or adhesive residue use Sika® MB, Sika® MB Redline, or Sika® MB EZ Rapid – see appropriate product data sheet for installation instructions and proper details. If surface contains asphalt (cutback) adhesive, follow the Resilient Floor Covering Institute “Recommended Work Practices” for removal. When the asphalt (cutback) adhesive is sufficiently removed use the Sika® MB, Sika® MB Redline, or Sika® MB EZ Rapid to help promote adhesion to the subfloor or use a Sika® Level patch/level product in conjunction with the correct primer.
- SikaBond®-T17 will adhere to most common patching / levelling compounds. Due to differences in asphalt-based adhesive types and performance capabilities, applicators must verify that preparation of the surface is sufficient prior to using Sika® MB or Sika® Level patch / level compound. For unknown substrates, please contact Sika® Technical Services for best practices at 1-800-933-SIKA.

APPLICATION METHOD / TOOLS

Read and understand data sheet completely before beginning installation. Follow all industry standards, as well as hardwood and bamboo flooring manufacturer’s recommendations for floor flatness, acclimation, design, layout, application, etc. of wood flooring material. If jobsite conditions are outside of flooring manufacturer’s recommendations, take necessary corrective actions as recommended by the floor manufacturer to address these issues. Whether the moisture content of substrate exceeds or is within the manufacturer’s recommendations, to address current or possible future subfloor moisture, apply SikaBond®-T17 as directed. SikaBond®-T17 is applied to the properly prepared substrate directly from the pail and uniformly distributed by trowel as described on this Product Data Sheet. Press the wood floor elements firmly into the adhesive so that the wood floor underside is sufficiently wetted. The elements can then be joined together using a rubber hammer and an impact block and/or rubber mallet. Many types of wood floors have to be tapped from the top. Leave gaps at room perimeters and at any floor wall partition to allow wood flooring to move naturally – follow recommended guidelines from wood

floor manufacturer. Spacers should be used to ensure perimeter space is maintained. The wood flooring manufacturer's laying instructions, acclimation requirements, room humidity/environmental control requirements as well as standard construction rules must be observed.

Plywood over concrete

Use a minimum 3/4" (19 mm) subfloor panel cut to smaller 2' x 8' or 4' x 4' sections. Kerf the back of the panels 1/2 the thickness of the material (3/8") on a 12" x 12" grid. Lay sections in a staggered joint pattern in the adhesive, with 1/8" spacing between sheets, and 3/4" minimum expansion space at walls and all vertical obstructions. Flatness tolerances should be to within 3/16" in 6' or 1/4" in 10' for nail down over the wood subfloor. Do not use flooring fasteners longer than 3/4" to be certain not to puncture the moisture control membrane. Using a Sika P5 trowel, apply adhesive/membrane to substrate and then set plywood into the wet adhesive/membrane. For adhesion only, ensure at least 90% coverage and transfer. For moisture control, ensure 100% coverage and transfer. Allow the adhesive/membrane to fully cure before nailing or using the SikaBond® adhesive/membrane to install flooring. Make sure that nails do not penetrate through the adhesive membrane.

Crack preparation

All moving joints and moving cracks must be honored up through the floor preparation and floor covering installation, finishing with an appropriate Sika flexible sealing compound. Dormant hairline cracks can be covered with Sika® MB, Sika® MB Redline or Sika® MB EZ Rapid. Dormant joints and dormant cracks greater than a hairline that will not be honored must be pre-filled in strict accordance with the installation instructions provided by the Sika Technical Service Department.

CLEANING OF TOOLS

All tools must be cleaned immediately after use with SikaBond® Remover or standard industry cleaning solvent. Any adhesive that is permitted to cure on the tool will need to be removed by mechanical means. SikaBond® Remover can be used to remove uncured or cured adhesive and fingerprints from wood surface.

OTHER RESTRICTIONS

See Legal Disclaimer.

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Product Data Sheet

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LEGAL DISCLAIMER

- KEEP CONTAINER TIGHTLY CLOSED
- KEEP OUT OF REACH OF CHILDREN
- NOT FOR INTERNAL CONSUMPTION
- FOR INDUSTRIAL USE ONLY
- FOR PROFESSIONAL USE ONLY

Prior to each use of any product of Sika Corporation, its subsidiaries or affiliates ("SIKA"), the user must always read and follow the warnings and instructions on the product's most current product label, Product Data Sheet and Safety Data Sheet which are available at usa.sika.com or by calling SIKA's Technical Service Department at 1-800-933-7452. Nothing contained in any SIKA literature or materials relieves the user of the obligation to read and follow the warnings and instructions for each SIKA product as set forth in the current product label, Product Data Sheet and Safety Data Sheet prior to use of the SIKA product.

SIKA warrants this product for one year from date of installation to be free from manufacturing defects and to meet the technical properties on the current Product Data Sheet if used as directed within the product's shelf life. User determines suitability of product for intended use and assumes all risks. User's and/or buyer's sole remedy shall be limited to the purchase price or replacement of this product exclusive of any labor costs. **NO OTHER WARRANTIES EXPRESS OR IMPLIED SHALL APPLY INCLUDING ANY WARRANTY OF MERCHANTABILITY OR FITNESS FOR A PARTICULAR PURPOSE. SIKA SHALL NOT BE LIABLE UNDER ANY LEGAL THEORY FOR SPECIAL OR CONSEQUENTIAL DAMAGES. SIKA SHALL NOT BE RESPONSIBLE FOR THE USE OF THIS PRODUCT IN A MANNER TO INFRINGE ON ANY PATENT OR ANY OTHER INTELLECTUAL PROPERTY RIGHTS HELD BY OTHERS.**

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